

Title (en)

METHOD AND APPARATUS FOR MONITORING A PROCESSING PROCESS OF A WORKPIECE BY MEANS OF A LASER BEAM

Title (de)

VERFAHREN UND VORRICHTUNG ZUR ÜBERWACHUNG EINES BEARBEITUNGSPROZESSES EINES WERKSTÜCKS MITTELS EINES LASERSTRAHLS

Title (fr)

PROCÉDÉ ET DISPOSITIF DE SURVEILLANCE D'UN PROCESSUS D'USINAGE D'UNE PIÈCE AU MOYEN D'UN FAISCEAU LASER

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Application

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Abstract (en)

[origin: WO2020069840A1] The invention relates to an apparatus for monitoring a laser processing process on a workpiece, comprising: a computing unit (16), which is configured to determine a dynamic processing position (TCPi) relative to a point of incidence (AP) of the laser beam (1) for a process parameter set (PPS) of the laser processing process by means of a model based on at least one stipulated comparison parameter set and an associated comparison processing position, and an observation unit (17), which is configured to determine at least one monitoring parameter of the laser processing process at the dynamic processing position (TCPi).

IPC 8 full level

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CPC (source: EP)

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